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	Material	Thickness	Constant	Board Layer Stack					
Overlay									
Solder	Solder Resist	0.010mm	3.5						
Layer	CF-004	0.035mm							
Tric 1	PP-023	0.218mm	4.5						
1	CF-004	0.035mm							
Tric1	Core-042	0.991mm	4.6						
2	CF-004	0.035mm							
Tric 2	PP-023	0.218mm	4.5						
n Layer	CF-004	0.035mm							
n Solder	Solder Resist	0.010mm	3.5						
n Overlay									

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 8 MIL

MIN. VIA PAD SIZE: 19 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

☐ FR-4

☒ FR-4 High Tg

☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER

☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH:

☐ IMMERSION GOLD (ENIG) ☐ ENEPIG

☐ IMM. TIN/SILVER OR EQUIV ☒ OTHER HASL

ARRAY/PANEL:

☐ CUT AND TRIM PER M1 BOARD OUTLINE

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION:

MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE

TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE:

TIEUM-MC-MODULE-F280013x

DESIGNED FOR:

Public Release

FILE NAME:

MCU155A_PCB.PcbDoc

of this specification design will meet use, or will operate in worthy. You should ty for your application.

ENGINEER:

Jason Osborn

LAYOUT BY:

SCALE: 1.00

ALTUM DESIGNER VERSION: 23.9.2.47

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